



Creative Materials, Inc.  
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**126-37-F**

**B-STAGED ANISOTROPIC CONDUCTIVE LOW CTE EPOXY ADHESIVE**

**DESCRIPTION:** 126-37-F is an anisotropically conductive transferable low CTE adhesive film. This product features excellent adhesion to Kapton, Mylar, glass and a variety of other substrates. 126-37 is designed to exhibit minimal flow during bonding. This product provides superior electrical conductivity when bonding circuit materials to metal back planes and heat sinks. This product has excellent adhesion to aluminum, ceramic, and a variety of other substrates. This system features excellent thermal stability and flexibility in the B-Staged form. Unlike conventional conductive materials, this product is very resistant to flexing and creasing. The product can be re-bonded many times by simply adding heat and slight pressure. Applications for 126-37-F include, but are not limited to, conductive splicing of ribbon cables, PTF circuits, and electrical attachment of surface mounted devices. This product is useful in application where shorts between closely spaced contacts is a concern. This product is available in thicknesses from 1 to 5 mils. Other thicknesses are available upon request.

**GENERAL FILM DESCRIPTION**

Substrate Type: PET Release Liner  
Conductive Coating Type: Silver/Polymer

Product Code	Adhesive Thickness (mils)
126-37-F1	1
126-37-F2	2
126-37-F3	3
126-37-F4	4
126-37-F5	5

**TYPICAL CURED PROPERTIES**

Property	Value	Units
Volume Resistivity (X,Y Axis)	1x10 <sup>12</sup>	Ω – cm
Volume Resistivity (Z Axis)	0.0001	Ω – cm
Thermal Stability	Good to +325	° C
Useful Temperature Range	-55 to +230	° C
Glass transition Temperature – Tg	150	° C
Coefficient of Thermal Expansion - Below Tg	50 x 10 <sup>-6</sup>	in/in/°C
- Above Tg	60 x 10 <sup>-6</sup>	in/in/°C
Tensile Shear Strength, min	2,000	Psi

**CURING GUIDELINES**

Temperature (°C)	Time (min.)
160	60
175	30
200	15

These temperatures and times are presented as a guide only. The end-user is encouraged to experiment to determine optimum curing schedule.

*All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.*

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**PROCEDURE FOR APPLYING 126-37-F**

1. As with all adhesive bonds, surface preparation is a vital part of the process. Carefully clean both surfaces to be bonded with MEK if possible. If MEK is not compatible with the surfaces to be bonded, another suitable solvent may be substituted.
2. Allow cleaned surfaces to dry for approximately 2-3 minutes.
3. Locate the adhesive onto the preheated substrate(s). Smooth out any trapped air by hand, with a roller or any other smoothing device. Some pressure is advisable to ensure intimate contact between the adhesive and substrate
4. Place the two surfaces together and cure using the guidelines above and enough pressure to hold the surfaces tightly together. Lower temperatures may be used but the cure times will be longer.
5. Allow to cool to room temperature under the same pressure.
6. Remove pressure. Part is ready for use.

**SHELF LIFE**

<b>Storage Temperature</b>	<b>B-Staged Film</b>
25°C	1 month
-10°C	3 months